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**COPPER ALLOY FOR CONDUCTIVE SPRING**

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**Abstract**

**PURPOSE:** To obtain a copper alloy having high strength and high conductivity and excellent in stress relaxation property, thermal peeling resistance of plating, silver plating suitability, and stress corrosion cracking resistance.

**CONSTITUTION:** The alloy is an alloy which has a composition containing 0.5-4.0% Ni, 0.1-1.0% Si, 0.01-0.1% Mg,  $\leq 0.0015\%$  S, and  $\leq 0.0015\%$  O or further containing, as accessory components, 0.005-1.0% of one or  $\geq 2$  elements among P, B, As, Fe, Co, Cr, Al, Sn, Ti, Zr, In, and Mn and further an alloy which has a composition containing, besides the above components, 0.01-15% Zn. This alloy can be used for terminal, connector, relay, switch, etc.

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